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## Peak EMI Reduction IC

### Features

- 1x Peak EMI Reduction IC
- Input Frequency: 18MHz-36MHz
- Output Frequency: 18MHz-36MHz
- Frequency Deviation @ 27MHz: -0.25%
- Modulation Rate @ 27MHz: 30.1KHz
- Supply Voltage: 3.3V  $\pm$  0.3V
- Operating current less than 8mA @ 27MHz
- Spread Spectrum Enable Control
- CMOS design
- 8L-WDFN (8L-TDFN) package

### Product Description

PCS3P2537A is a 1x spread spectrum frequency modulator designed to reduce electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of down stream clock and data dependent signals. The device allows significant system cost savings by reducing the number of circuit board layers, ferrite beads and shielding and other passive components that are traditionally required to pass EMI regulations.

PCS3P2537A modulates the output of a single PLL in order to “spread” the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This result in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal’s bandwidth is called ‘spread spectrum clock generation.’

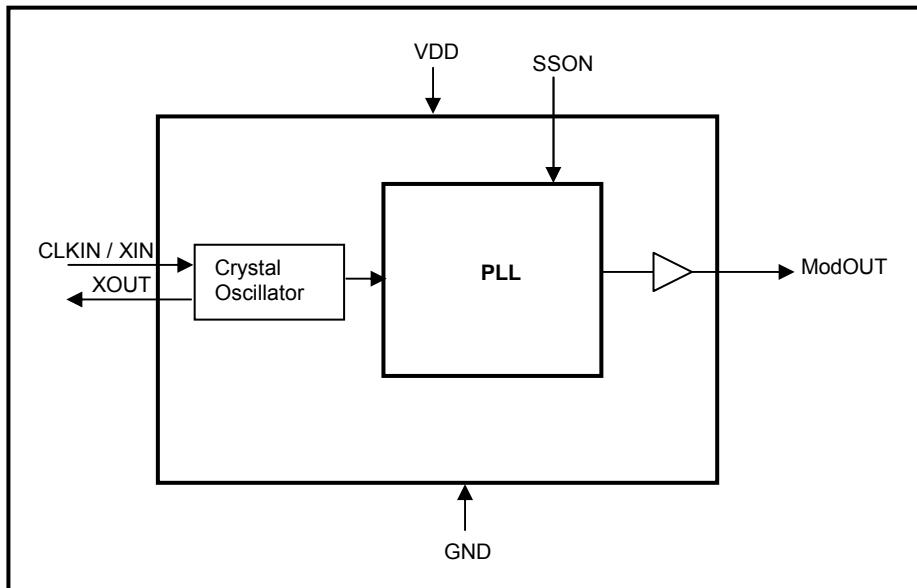
PCS3P2537A has a frequency range of 18MHz-36MHz, and accepts input clock either from a Crystal or from an external reference and locks on to it delivering a 1x spread spectrum clock output. It has an SSON control for enabling and disabling Spread Spectrum function.

PCS3P2537A operates with a supply voltage of 3.3V, and is available in 8 L-WDFN package.

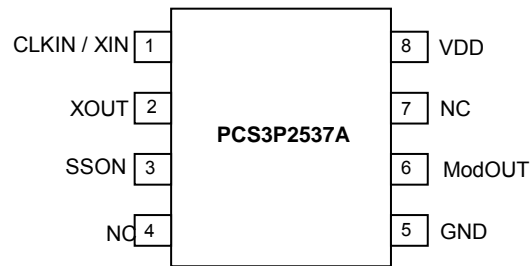
### Application

PCS3P2537A is targeted towards PC peripheral devices and embedded systems.

### Block Diagram



## Pin Configuration (8L-WDFN Package)



## Pin Description

Pin#	Pin Name	Type	Description
1	CLKIN / XIN	I	External reference Clock input or Crystal connection. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
2	XOUT	O	Crystal connection. If using an external reference, this pin must be left unconnected.
3	SSON	I	When SSON is HIGH, the spread spectrum is enabled and when LOW, it turns off the spread spectrum.
4	NC		No Connect.
5	GND	P	Ground connection.
6	ModOUT	O	Spread Spectrum Clock Output.
7	NC		No Connect.
8	VDD	P	Power supply for the entire chip.

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit
VDD, VIN	Voltage on any pin with respect to Ground	-0.5 to +4.6	V
T <sub>STG</sub>	Storage temperature	-65 to +125	°C
T <sub>s</sub>	Max. Soldering Temperature (10 sec)	260	°C
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>DV</sub>	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

**Operating Conditions**

Parameter	Description	Min	Max	Unit
VDD	Supply Voltage	3.0	3.6	V
T <sub>A</sub>	Operating Temperature (Ambient Temperature)	0	70	°C
C <sub>L</sub>	Load Capacitance		15	pF
C <sub>IN</sub>	Input Capacitance		7	pF

**DC Electrical Characteristics for 3.3V Supply**

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>IL</sub>	Input low voltage	VSS-0.3		0.8	V
V <sub>IH</sub>	Input high voltage	2.0		VDD+0.3	V
I <sub>IL</sub>	Input low current			-35	µA
I <sub>IH</sub>	Input high current			35	µA
V <sub>OL</sub>	Output low voltage (VDD = 3.3V, I <sub>OL</sub> = 8mA)			0.4	V
V <sub>OH</sub>	Output high voltage (VDD = 3.3V, I <sub>OH</sub> = 8mA)	2.5			V
I <sub>DD</sub>	Static supply current <sup>1</sup>			2.5	mA
I <sub>CC</sub>	Dynamic supply current (3.3V, 27MHz and no load)		5	8	mA
VDD	Operating Voltage	3	3.3	3.6	V
t <sub>ON</sub>	Power-up time (first locked cycle after power-up)			5	mS
Z <sub>OUT</sub>	Output impedance		36		Ω

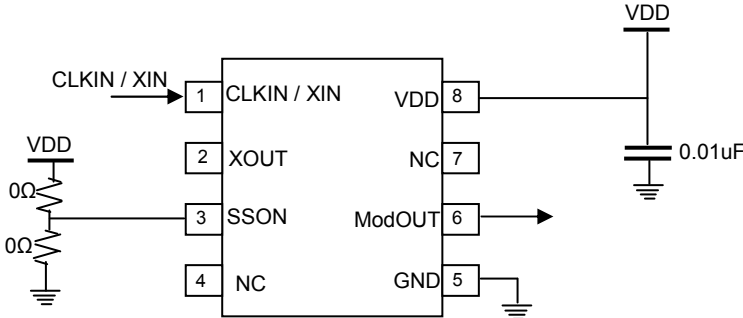
Note: 1. CLKIN is pulled to GND.

**AC Electrical Characteristics for 3.3V Supply**

Symbol	Parameter	Min	Typ	Max	Unit
CLKIN	Input frequency	18	27	36	MHz
ModOUT	Output frequency	18	27	36	MHz
$f_d$	Frequency Deviation @ 27MHz	-0.2	-0.25	-0.3	%
MR	Modulation Rate @ 27MHz	30		33	KHz
$t_{LH}^1$	Output rise time (measured from 20% to 80%)			2	nS
$t_{HL}^1$	Output fall time (measured at 80% to 20%)			1.5	nS
$t_{JC}$	Cycle-to-Cycle Jitter at 27MHz		±200	±300	pS
$t_D$	Output duty cycle	45	50	55	%

Note: 1.  $t_{LH}$  and  $t_{HL}$  are measured into a capacitive load of 15pF.

**Typical Application Schematic**



Note: Refer to Pin Description table for Functionality Details.

**PCB Layout Recommendation**

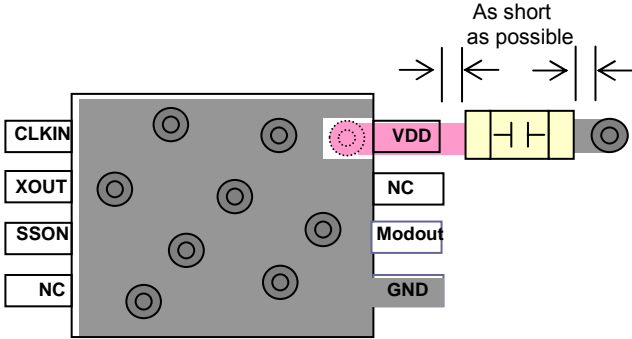
For optimum device performance, the following guidelines are recommended.

- Dedicated VDD and GND planes.
- The device must be isolated from system power supply noise. A 0.01μF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be

used between the decoupling capacitor and VDD pin. The PCB trace to VDD pin and the ground via should be kept as short as possible. All the VDD pins should have decoupling capacitors.

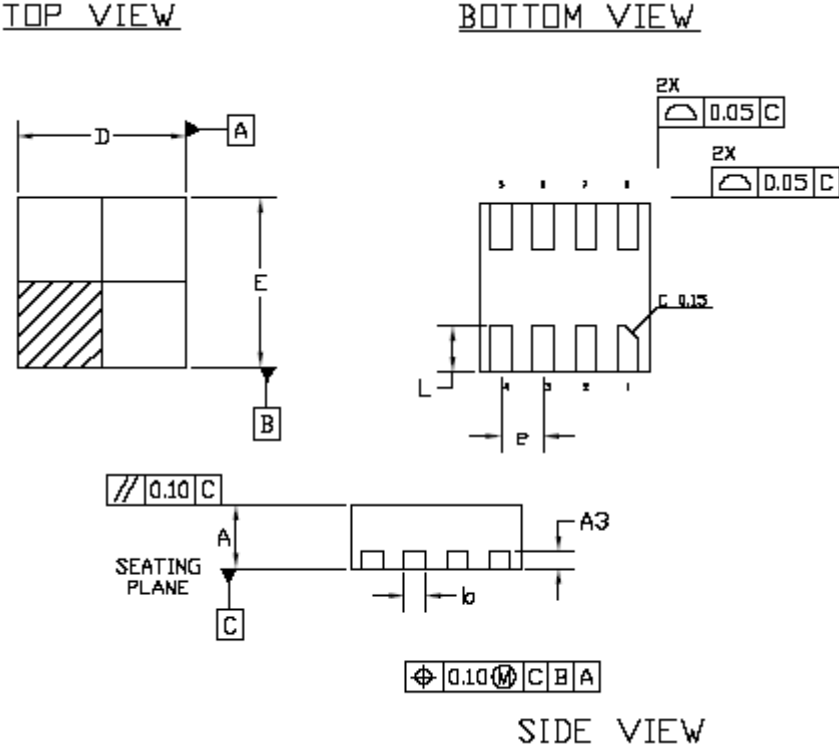
- In an optimum layout all components are on the same side of the board, minimizing vias through other signal layers.

A typical layout is shown in the figure



Package Information

8L-WDFN package




Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.027	0.0315	0.70	0.80
A3	0.008 BSC		0.203 BSC	
b	0.008	0.012	0.20	0.30
D	0.077	0.080	1.95	2.05
E	0.077	0.080	1.95	2.05
e	0.020 BSC		0.50 BSC	
L	0.020	0.024	0.50	0.60

## Ordering Code

Part Number	Top Marking	Package	Temperature
PCS3P2537AG-08CR	AM	8L-WDFN (8L-TDFN) - TAPE & REEL, Green	0°C to +70°C

A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-free.

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